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(54) Title: SPACER FILL STRUCTURE, METHOD AND DESIGN STRUCTURE FOR REDUCING DEVICE VARIATION

(57) Abstract: A design structure (100, FIG. 1a) is provided for spacer fill structures (100 and 300) and, more particularly, spacer fill structures (100 and 300), a method of manufacturing and a design structure for reducing device variation is provided. The structure includes a plurality of dummy fill shapes (100) in different areas of a device which are configured such that gate perimeter to gate area ratio will result in a total perimeter density being uniform across a chip.

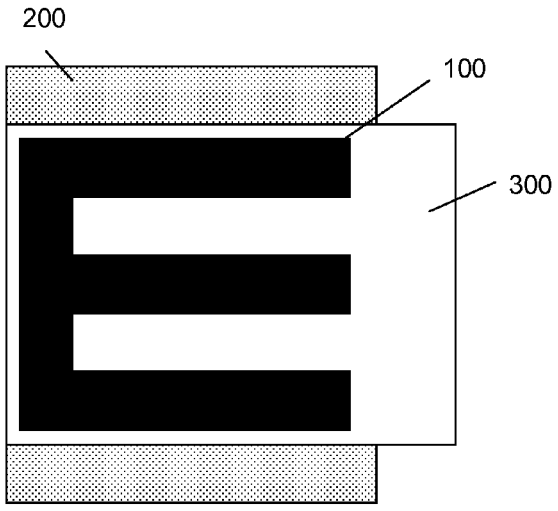

FIG. 1a

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